OIF TO DEMONSTRATE CEI INTEROPERABILITY AT DESIGNCON 2005

Participating Members to Demonstrate Interoperability of New CEI Implementation Agreement

FREMONT, CA – January 20, 2005 – The Optical Internetworking Forum (OIF) announced today that six of its member companies will demonstrate interoperability functionality using the OIF’s recently approved Common Electrical I/O (CEI) Implementation Agreement (IA). The demonstration will take place at DesignCon 2005, February 1 – 2, during exhibit hours (12:30 pm – 6:30 pm) at the Santa Clara Convention Center. The interoperability demonstration will be conducted at the OIF’s DesignCon booth, (# 907) and will include Altera, Interconnect Technologies (A Northrop Grumman company), Molex®, Tyco Electronics, Vitesse and Xilinx. Member companies Agilent Technologies Inc. and Tektronix, Inc. will provide test equipment for the CEI demonstration.

In response to an industry-wide demand for 6G and 11G high-speed electrical interface standards, the OIF developed implementation agreements for 6G short reach, 6G long reach and 11G short reach interfaces as a viable I/O solution for high-speed systems.

Successful interoperability will be demonstrated from 8 to 49 inches of transmission lines at 6G and 11G. Legacy-type materials and configurations as well as channels targeted at greenfield applications will be demonstrated at 6G, while the 11G interoperability channels are greenfield type applications including “improved FR-4 materials and backdrilled vias”.

Contact:
Kendra Bellah
Porchivina & Associates
Office: 415-893-9138
Mobile: 415-246-6061
Email: kendra@papr.com
"The inexorable rise in line data rates provide a continual challenge for equipment and IC designers addressing the telecom and enterprise markets," said Roy Rubenstein, senior analyst at market research and advisory company, RHK Inc. "The demonstrated workings of the latest CEI 6G and 11G interfaces, developed in only two years, is an impressive achievement. The industry is now equipped with denser interfaces to meet current and future equipment design challenges."

“The participating members, by demonstrating interoperability, are promoting the acceptance and viability of CEI,” said Brian Von Herzen of Xilinx, and OIF Interoperability Working Group co-chair. “The OIF recognized early on that the industry needed a 6G and 11G IA and successfully brought together a wide variety of vendors to show that CEI is a reality today.”

OIF Presentation at DesignCon

The OIF will address DesignCon attendees on Tuesday, February 1st at 8:30am in Ballroom H. As part of the TecPreview track at DesignCon, the OIF will discuss details of the CEI IA interoperability demonstration.

CEI IA

The OIF’s Common Electrical I/O IA for 6G+ bps and 11G+ bps interfaces was finalized in 2004. Applications covered by the IA include high-speed backplanes, chip-to-chip interconnect and chip to optical module interfaces. The three electrical interfaces included in the IA are: CEI-6G-SR 6 Gigabit Short Reach (4.976 to 6.375 Gigabit per second, 0 to 200 mm of printed circuit board and 1 connector); CEI-6G-LR 6 Gigabit Long Reach (4.976 to 6.375 Gigabit per second, 0 to 1 Meter of printed circuit board and up to 2 connectors); and CEI-11G-SR 11 Gigabit Short Reach (9.95 to 11.1 Gigabits per second, 0 to 200 mm of printed circuit board and 1 connector). CEI-11G-LR 11 Gigabit Long Reach (9.95 to 11.1 Gigabits per second, 0 to 1 Meter of printed circuit board and up to 2 connectors) interface is under development.
About the OIF

Launched in April of 1998, the OIF is a non-profit organization with a unique and diverse member base, including many of the world's leading carriers, component manufacturers and system vendors. As the only industry group uniting representatives from data and optical networks, the OIF helps advance the standards and methods of optical networks. The purpose of the OIF is to accelerate the deployment of interoperable, cost-effective and robust optical networks and their associated technologies. Optical internetworks are data networks composed of routers and data switches interconnected by optical networking elements.

With the goal of promoting worldwide compatibility of optical internetworking products, the OIF actively supports and extends the work of national and international standards bodies. Liaisons have been established with The ATM Forum, IEEE 802.3, IETF, ITU-T Study Group 13, ITU-T Study Group 15, MEF, NPF, OPTXS, Rapid I/O, TMF MTNM group, TMOC, UXPI and the XFP MSA Group. More information on the OIF can be found at www.oiforum.com.

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